



Material Content Data Sheet



Halogen-Free

Sales Product Name IPD85P04P4-07

Issued

24. February 2022

MA# MA005700791

Package PG-TO252-3-313

Weight*

319.66 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.544	0.80	0.80	7960	7960
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		461	
	non noble metal	copper	7440-50-8	147.096	46.02	46.08	460170	460769
wire	non noble metal	aluminium	7429-90-5	5.244	1.64	1.64	16404	16404
encapsulation	inorganic material	zinc oxide	1314-13-2	1.379	0.43		4314	
	miscellaneous	miscellaneous	-	6.895	2.16		21569	
	plastics	epoxy resin	-	20.684	6.47		64707	
	inorganic material	silicon dioxide	60676-86-0	108.935	34.08	43.14	340788	431378
lead finish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11700	11700
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4444	4455
solder	non noble metal	tin	7440-31-5	0.046	0.01		145	
	noble metal	silver	7440-22-4	0.058	0.02		182	
	non noble metal	lead	7439-92-1	2.217	0.69	0.72	6935	7262
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.00	6.01	59994	60072
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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